

Reliability and Test Condition

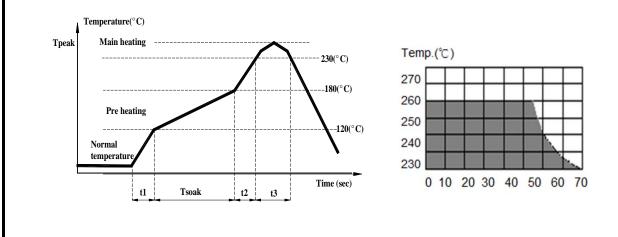
ITEM	SPECIFICATION	TEST CONDITIONS
Operating Temperature	- 55 °C ∼ + 125 °C	
Storage Temperature	- 40 °C ∼ + 85 °C	

Reflow soldering conditions

Temperature rise gradient	t1	1~5°C/sec
Heating time Heating temperature	Tsoak	$50s \sim 150s$ $120^{\circ}C \sim 180^{\circ}C$
Time over 230°C	t3	90~120 sec
Slope of temp. rise	t2	1~5°C/sec
Peak temperature Peak hold time	Tpeak	255∼260°C 10sec (max)
	-	No. of mounting 3 times

- Pre-heating should be in such a way that the temperature difference between solder and ferrite surface is limited to 150°C max. Also cooling into solvent after soldering should be in such a way that the temperature difference is limited to 100°C max. Unenough pre-heating may cause cracks on the ferrite, resulting in the deterioration of product quality.
- Products should be soldered within the following allowable range indicated by the slanted line. The excessive soldering conditions may cause the corrosion of the electrode, When soldering is repeated, allowable time is the accumulated time.

Reflow soldering temperature profile





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ITEM	SPECIFICATION	TEST CONDITIONS	
Reworking with soldering iron			
• Preheating : 150° C, 1 minute			
 Tip temperat 	• Tip temperature : 280° C max.		
• Soldering time : 3 seconds max.			
• Soldering iron output : 30w max.			
• End of soldering iron : ϕ 3mm max.			
• Reworking should be limited to only one time.			
Note: Do not directly touch the products with the tip of the soldering iron in order to			
prevent the crack on the ferrite material due to the thermal shock.			
Solder Volume	Solder Volume		
• Solder shall	be used not to be exceed the upper limits as show	vn below.	
Upper Limit			
		- Recommendable	
 Accordingly increasing the solder volume, the mechanical stress to product is also increased. Exceeding solder volume may cause the failure of mechanical or electrical performance. 			

MECHANICAL CHARACTERISTICS

ITEM	SPECIFICATION	TEST CONDITIONS
Terminal Strength	Terminal strength does not distort the case shall meet SPEC DC resistance specifications.	Solder chip on PCB and applied 10N (1.02Kgf) for 10 sec. CHIP BEAD F
Substrate bending test	SPEC substrate bending test DC resistance shall meet specifications.	 After soldering a chip to a test substrate, bend the substrate by 3mm hold for 10s and then return. Soldering shall be done in accordance with the recommended PC board pattern and reflow soldering.



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ITEM	SPECIFICATION	TEST CONDITIONS
Resistance to solder heat	• No visible damage	• Solder Temp. : $265\pm3^{\circ}C$
	• Electrical characteristics and mechanical	• Immersion time : 6±1 sec
	characteristics shall be satisfied.	• Preheating : 100° C to 150° C, 1 minute.
		• Measurement to be made after keeping
	Consult standard MIL-STD-202	keeping at room temp for 24±2 hrs.
	METHOD 210	· Solder : Sn-3Ag-0.5Cu
Solderability	• 95% min. coverage of all metabolised area	• Solder Temp. : $240\pm5^{\circ}C$
		• Immersion time : 3±1 sec
	Consult standard J-STD-002	· Solder : Sn-3Ag-0.5Cu

Environmental Characteristics

ITEM	SPECIFICATION	TEST CONDITIONS
High Temperature Resistance	 Appearance : no mechanical damage Inductance shall be with ±20% of the initial value 	 Operate Temperature : 125°C ± 2°C Time : 1000 ±12Hrs Measurement : After placing at room ambient temperature for 24 hours minimum
Biased Humidity Resistance	 Appearance : no mechanical damage Inductance shall be with ±20% of the initial value 	 Humidity : 85 ± 5% RH Temperature : 85°C ± 2°C Time : 1000 ±12Hrs Measurement : After placing at room ambient temperature for 24 hours minimum
Temperature Cycle	 Appearance : no mechanical damage Inductance shall be with ±20% of the initial value 	 Low Temperature : -55 ± 5°C kept stabilized for 30 minutes each High Temperature : 125 ± 5°C kept stabilized for 30 minutes each Cycle : 1000 cycles Measurement : After placing for 24 hours minimum at room ambient temperature step155°C temp±5°C 30±3 minutes step2. Room temperature 2 to 5 minutes step3. +125°C temp±5°C 30±3 minutes step4. Room temperature 2 to 5 minutes
Vibration test	 Appearance : no mechanical damage Inductance shall be with ±20% of the initial value 	 Frequency and Amplitude : 10-2000-10Hz Direction : X, Y, Z. Test duration : 4 hours for each direction, 12 hours in total.



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ITEM	SPECIFICATION	TEST CONDITIONS
Mechanical Shock Test Operational Life	 Appearance : no mechanical damage Inductance shall be with ±20% of the initial value 	 peak acceleration : 100g's Duration of pulse : 6 ms Waveform : Half-sine Velocity change : 12.3 ft/sec Direction : X , Y , Z (3 axes/3 times) Temperature : 125°C ± 2°C
	 Appearance : no mechanical damage Inductance shall be with ±20% of the initial value 	 Temperature : 125 C ± 2 C Time : 1000 ±12Hrs Measurement : After placing at room ambient temperature for 24 hours minimum
Electrostatic discharge test	 Appearance : no mechanical damage Inductance shall be with ±20% of the initial value 	 ESD voltage ; 15K Volts Mode 1 : 150 pF / 330 Ohm Mode 2 : 150 pF / 2000 Ohm